



- NOTES:**
1. Layers: 2
 2. PCB Thickness: 1.6 mm
 3. PCB Color: GREEN
 4. Material Type: FR-4 TG155
 5. Surface Finish: HASL
 6. Outer Copper Weight: 1 oz
 7. Impedance Control: NO
 8. Layer Stackup: xxxx
 9. Via Covering: Plugged
 10. Min Via Hole Size / Diameter:
0.406 mm / 0.81 mm
 11. Board Outline Tolerance: +/- 0.2 mm
 12. Silk Screen: INK-JET/SCREEN PRINTING
 13. Stencil Framework: YES
 14. Sencil Polishing: Electropolishing
 15. Fiducials: Etched Through
 16. Engrave Text

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	62.68 mils
Board overall dimensions:	3937.00 mils x 3110.00 mils		
Min track/spacing:	10.00 mils / 7.73 mils	Min hole diameter:	16.00 mils
Copper Finish:	HAL SnPb	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Drill Map:

- x 0.406mm / 0.0160" (37 holes)
- o 0.600mm / 0.0236" (0 holes + 4 slots)
- + 0.800mm / 0.0315" (12 holes)
- 0.900mm / 0.0354" (4 holes)
- ◇ 0.991mm / 0.0390" (4 holes)
- ⊗ 1.100mm / 0.0433" (8 holes)
- ※ 1.295mm / 0.0510" (4 holes)
- ⊗ 1.000mm / 0.0394" (2 holes) (not plated)
- ⊗ 1.152mm / 0.0454" (4 holes) (not plated)
- ⊕ 2.700mm / 0.1063" (4 holes) (not plated)

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	White	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.38 mils		1	0
Dielectric 1	core	FR4	59.12913 mils	FR4 natural	4.5	0.02
B.Cu	copper		1.38 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	White	1	0



1868 SPACE COOKIES

Sheet: File: NX-J401-Adapter.kicad_pcb		
Title: NX Adapter Board		
Size: B	Date: 2025-10-19	Rev: 5
KiCad E.D.A. 9.0.4		Id: 1/1